## Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

## Listing of Claims:

1. (Currently Amended) An electrostatic chuck having a bonded structure comprising a ceramic electrostatic chuck member, a metal member, and a bonding layer; said ceramic electrostatic chuck member and the metal member being bonded with said boding bonding layer;

wherein said bonding layer has comprises at least a first most outeroutermost bonding layer being bonded to said ceramic electrostatic chuck member, a second most outeroutermost bonding layer being bonded to said metal member, and a polyimide layer being disposed between said first and second most outeroutermost bonding layers, and wherein each of most outersaid first and second outermost bonding layers is made of eithercomprises a silicone layer or an acrylic layer.

- 2. (Currently Amended) The electrostatic chuck according to claim 1, wherein the thickness of the said bonding layer is 0.05 to 0.5 mm.
- 3. (Currently Amended) The electrostatic chuck according to claim 1, wherein the said ceramic electrostatic chuck member has a base material made of aluminum nitride, and said base material is being-formed as an integrated body by sintering it with an electrostatic chuck electrode being-embedded thereintotherein.
- 4. (Currently Amended) The electrostatic chuck according to claim 1, wherein a flatness of an adsorption surface in theof said ceramic electrostatic chuck member is 30 µm or less.



5. (Currently Amended) A method for manufacturing an electrostatic chuck having a bonded structure comprising a ceramic electrostatic chuck member, a metal member, and a bonding layer;— said ceramic electrostatic chuck member and the said metal member being bonded with said boding bonding layer, wherein said bonding layer has at least a first mest outeroutermost bonding layer being bonded to said ceramic electrostatic chuck member, a second most-outeroutermost bonding layer being bonded to said metal member, and a polyimide layer being disposed between said first and second most outeroutermost bonding layers, and wherein each of most outersaid first and second outermost bonding layers is made of eithercomprises a silicone layer or an aerylic layer; wherein, said method comprises-comprising the steps of:

Sign

preparing a sheet comprising at least a-said first most-outermost layer, said second most outeroutermost layer-made of either a-silicone layer or an acrylic layer, and an intermediate layer being disposed between said first and second most outeroutermost layers, and made of asaid intermediate layer comprising said polyimide layer;

sandwiching said sheet between said ceramic electrostatic chuck member and said metal member;

vacuum-packing said <u>ceramic</u> electrostatic chuck member, said <del>bonding</del> layer, <u>sandwiched sheet and</u> said metal layer-member and said sheet being sandwiched between said electrostatic chuck member and said metal-member-into a vacuum-packing bag; and

heating the thus vacuum-packed <u>ceramic</u> electrostatic chuck member, bonding <u>layersandwiched sheet</u> and metal <u>layer-member</u> under isotropic pressurization to bond them firmly.

## Amendments to the Abstract:

Please amend the Abstract as shown below:

## Abstract of the Disclosure

An electrostatic chuck having and a method for manufacturing the same are provided. The electrostatic chuck has a bonded structure comprising a ceramic electrostatic chuck member, a metal member and a bonding layer; the. The bonding layer having has at least a first most outeroutermost bonding layer being joined to the ceramic electrostatic chuck member, a second most outeroutermost bonding layer being joined to the metal member, and a an intermediate polyimide layer as an intermediate layer disposed between the first and second most outeroutermost bonding layers, and each. Each of the most outeroutermost bonding layers being are made of a silicone layer or an acrylic layer, and a method for manufacturing the same are provided: the bonding layer being excellent in airtightness, bonding strength, and corrosion resistance, free from bleeding of bonding material even under high pressures at time of joining, and the junction body being good in heat conductivity, and having a good flatness of its adsorption surface, with a small deformation due to temperature change.

